

更改 REV	註 MODIFICATION
A	EC04203
B	EC04206
C	EC04217

**Note:**

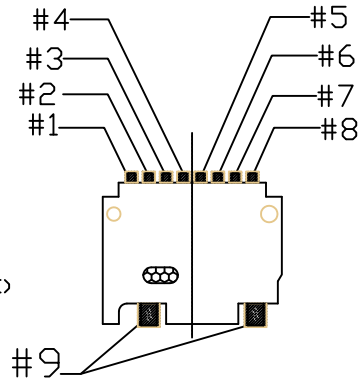
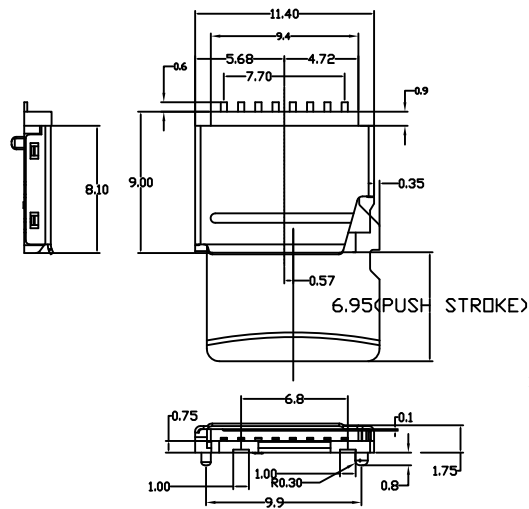
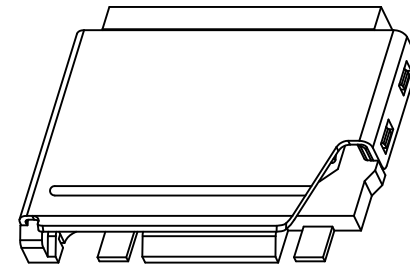
**1.Material:**

Housing: LCP  
 Contact: C5210-SH, T: 0.20 mm  
 Shell: SPCC, T: 0.20 mm

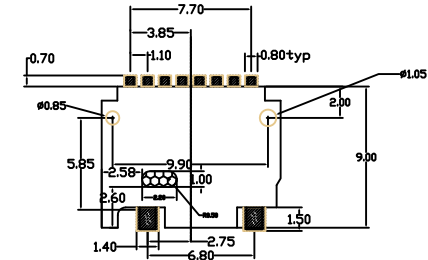
**2.Plating:**

Contact: G.F on contact area and Ni over all area for underplated  
 Mate tin 50 u' min in solder tail

Shell: Ni 50 u' min in all area



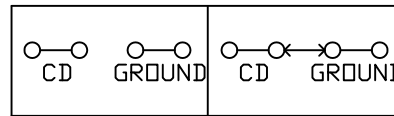
PIN NO	DESCRIPTION
#1	D2
#2	D3
#3	CD
#4	CMD
#5	PW
#6	CLK
#7	D0
#8	D1
#9	GND



RECOMMENDED PC BOARD LAYOUT  
 TOLERANCE: ±0.05mm

RECOMMENDED PC BOARD LAYOUT  
 (component side) TOLERANCE: ±0.05mm

**CIRCUIT:**

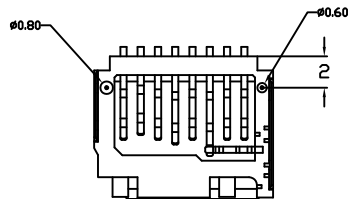


WITHOUT  
 CARD

MICRO SD  
 CARD  
 INSERTED

7MSDP-FA-X019

0:TRAY  
 1:RELL



GENERAL TOLERANCE		KINGCONN 皇海科技股份有限公司	
X± 0.50	X°± 5°	名 稱/TITLE MICRO SD CONN-1.75H	
X± 0.30	X°± 2°		
.XX± 0.20	.XX°± 1°		
單 位(UNIT) mm	料 號(PART NO.) 7MSDP-FA-X019	圖 號(DWG NO.) 7MSDP-FA-X019-c	SCALE 1:1
審 核(APPROVAL)	檢 查(CHECKED)	製 圖(DRAWN)	張 數(SHEET) 1/1
			更 改(REV) C

